



## General Description

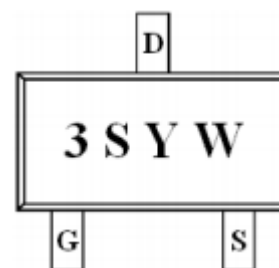
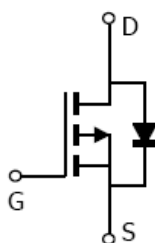
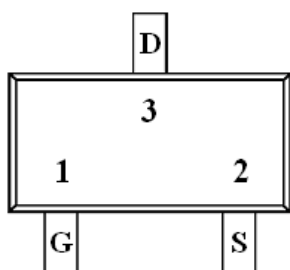
AFP3401S, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

## Features

- $I_D = -4.0A, R_{DS(ON)} = 65m\Omega @ V_{GS} = -10.0V$
- $I_D = -3.2A, R_{DS(ON)} = 80m\Omega @ V_{GS} = -4.5V$
- $I_D = -1.0A, R_{DS(ON)} = 105m\Omega @ V_{GS} = -2.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- SOT-23-3L package design

## Pin Description ( SOT-23-3L )



## Application

- Power Management in Note book
- LED Display
- DC-DC System
- LCD Panel

## Pin Define

Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFP3401SS23RG	3SYW	SOT-23-3L	Tape & Reel	3000 EA

- ※ 3S parts code
- ※ Y year code ( 0 ~ 9 )
- ※ W week code ( A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52 )
- ※ AFP3401SS23RG : 7" Tape & Reel ; Pb- Free ; Halogen -Free



### Absolute Maximum Ratings

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-30	V
Gate –Source Voltage	V <sub>GSS</sub>	±12	V
Continuous Drain Current(T <sub>J</sub> =150°C)	I <sub>D</sub>	T <sub>A</sub> =25°C	-4.0
		T <sub>A</sub> =70°C	-3.2
Pulsed Drain Current	I <sub>DM</sub>	-15	A
Continuous Source Current(Diode Conduction)	I <sub>S</sub>	-1.5	A
Power Dissipation	P <sub>D</sub>	T <sub>A</sub> =25°C	1.25
		T <sub>A</sub> =70°C	0.8
Operating Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	120	°C/W

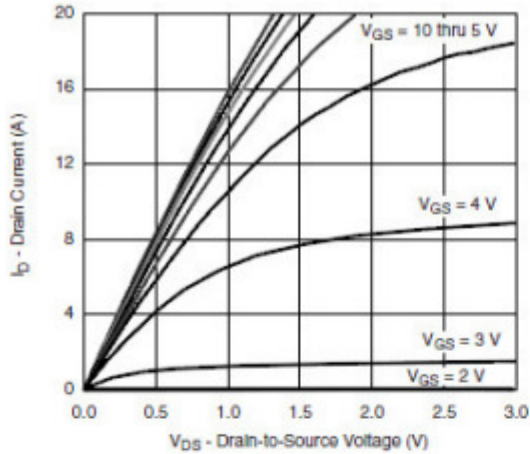
### Electrical Characteristics

(T<sub>A</sub>=25°C Unless otherwise noted)

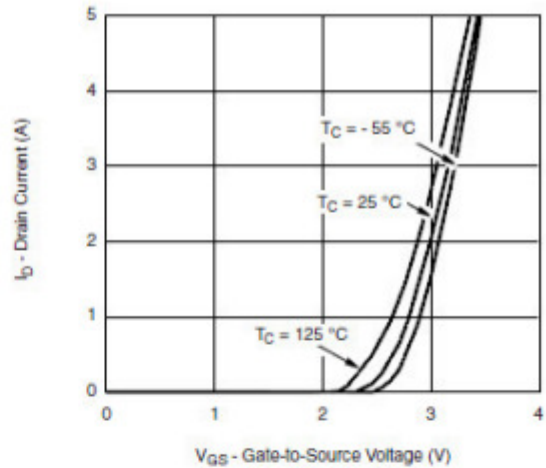
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-0.6		-1.1	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V			-1	uA
		V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V T <sub>A</sub> =85°C			-30	
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≤ -5V, V <sub>GS</sub> =-4.5V	-6			A
		V <sub>DS</sub> ≤ -5V, V <sub>GS</sub> =-2.5V	-3			
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10.0V, I <sub>D</sub> =-4.0A		55	65	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3.2A		65	80	
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-1.0A		82	105	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-2.8A		6.5		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-1.0A, V <sub>GS</sub> =0V		-0.7	-1.3	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V I <sub>D</sub> ≡-4.0A		10	18	nC
Gate-Source Charge	Q <sub>gs</sub>			1.6		
Gate-Drain Charge	Q <sub>gd</sub>			3.0		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V f=1MHz		450		pF
Output Capacitance	C <sub>oss</sub>			95		
Reverse Transfer Capacitance	C <sub>rss</sub>			55		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-15V, R <sub>L</sub> =15Ω I <sub>D</sub> ≡-1.0A, V <sub>GEN</sub> =-10V R <sub>G</sub> =6Ω		8	18	ns
	t <sub>r</sub>			8	18	
Turn-Off Time	t <sub>d(off)</sub>			25	50	
	t <sub>f</sub>			25	35	



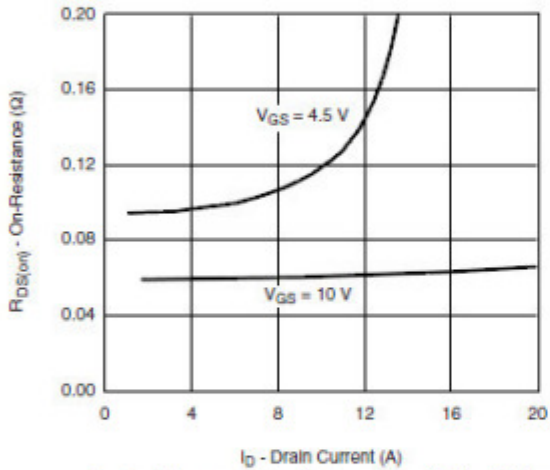
## Typical Characteristics



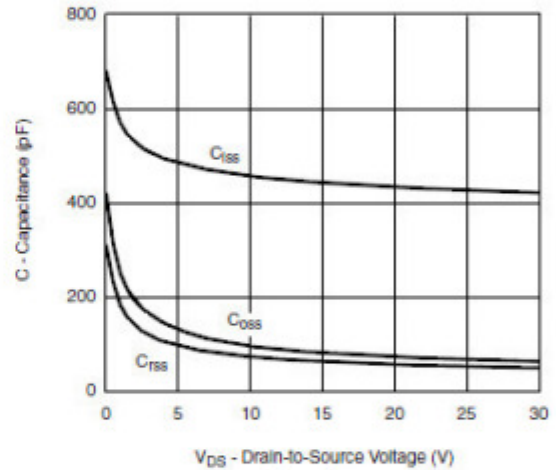
Output Characteristics



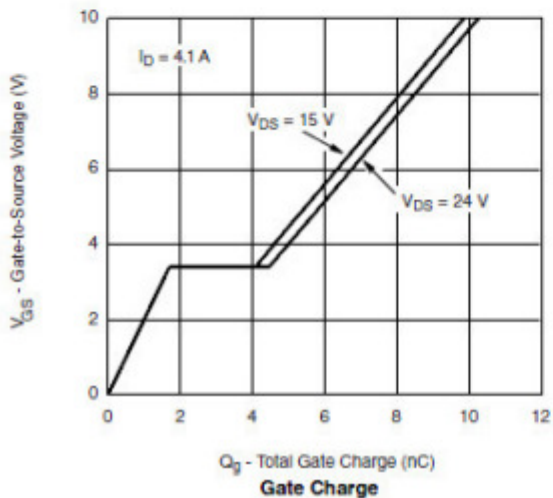
Transfer Characteristics



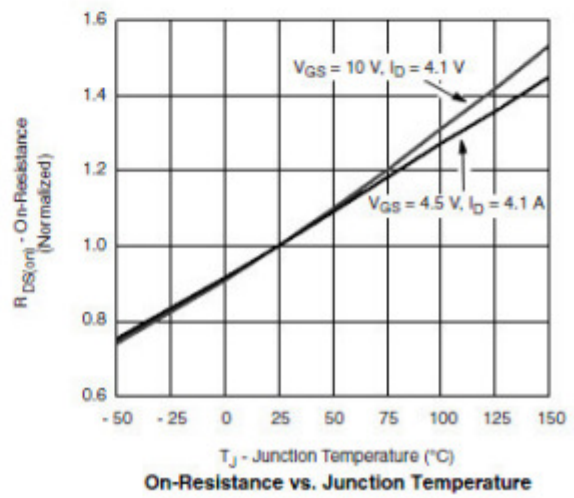
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



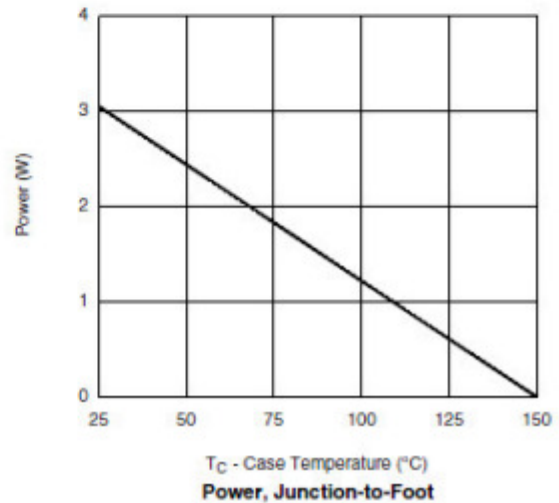
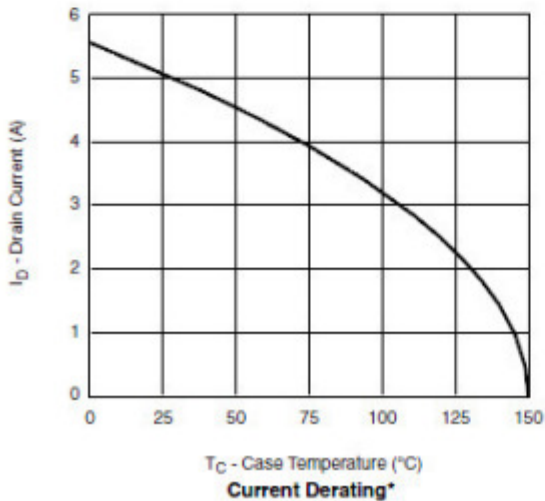
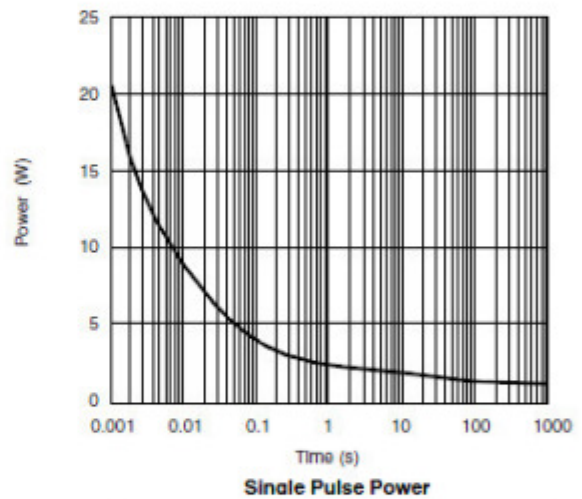
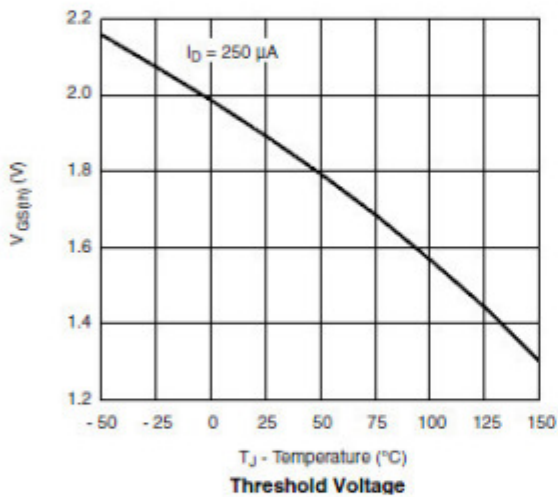
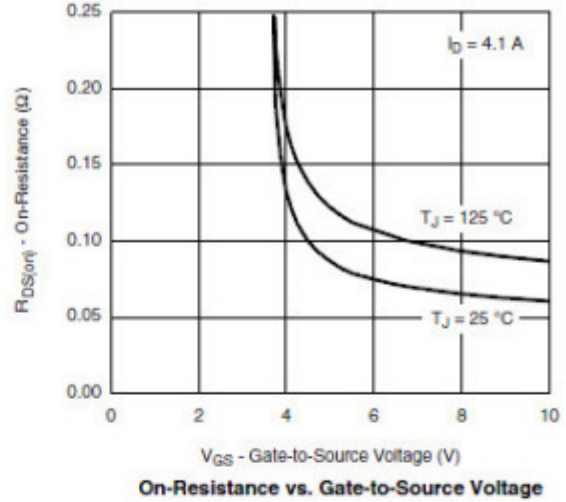
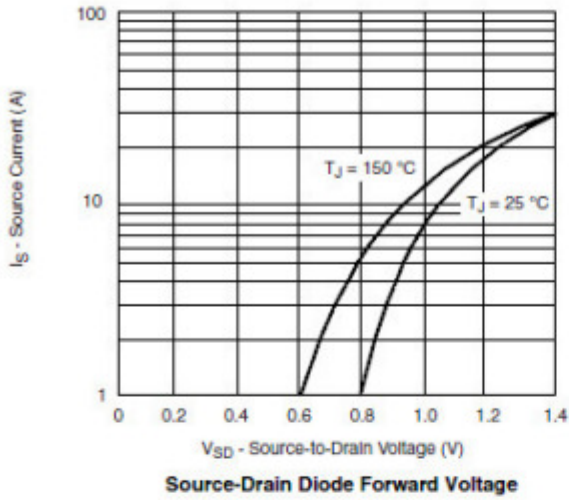
Gate Charge



On-Resistance vs. Junction Temperature

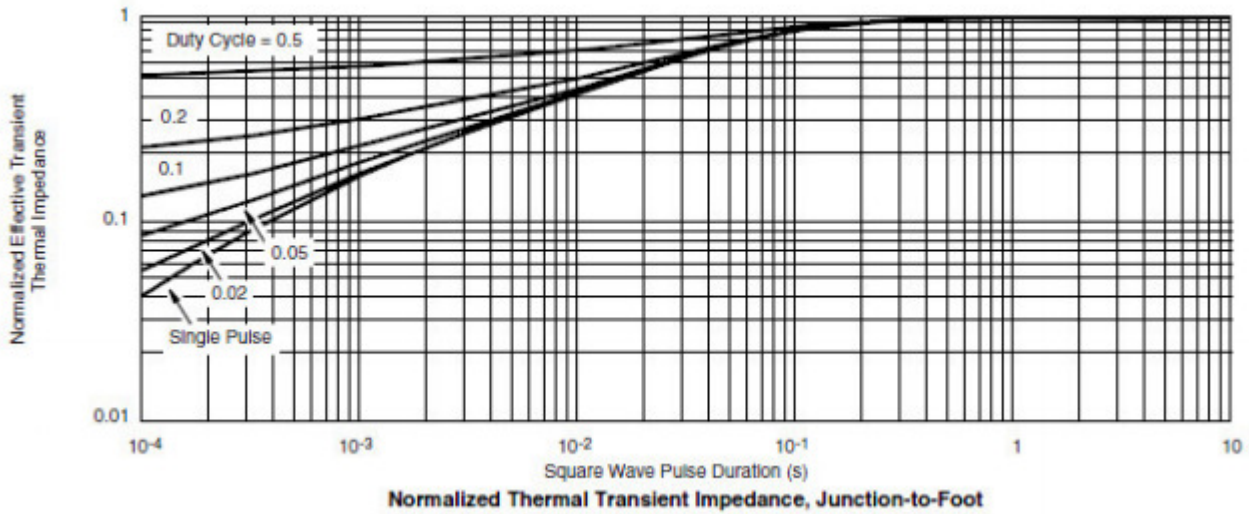
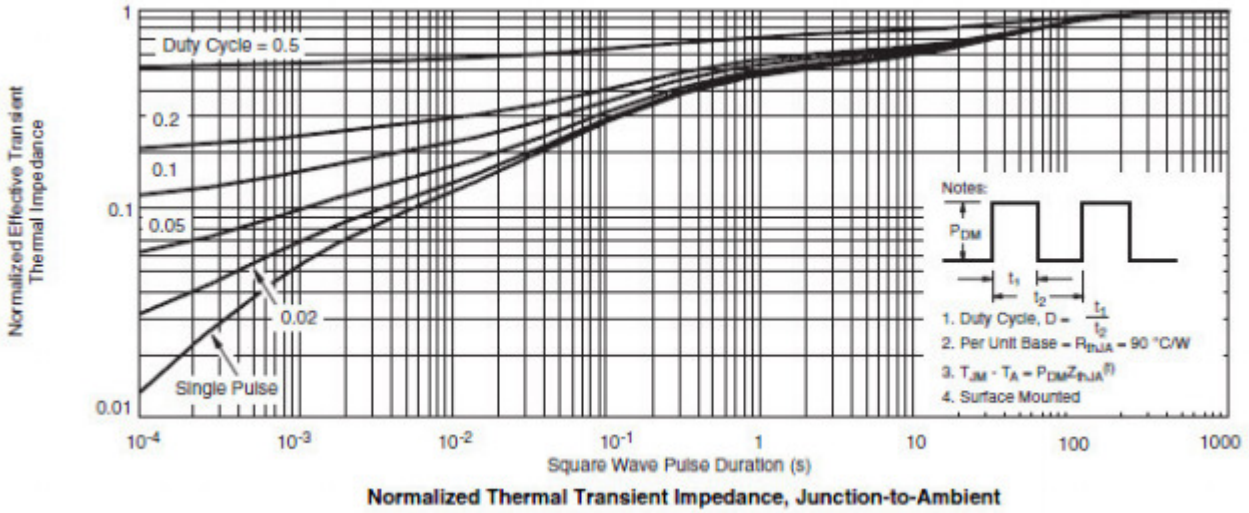


## Typical Characteristics





## Typical Characteristics

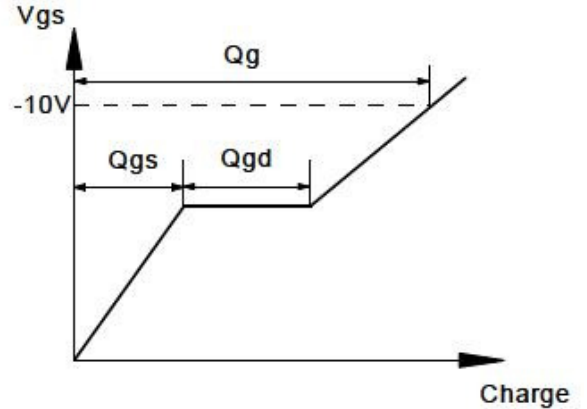
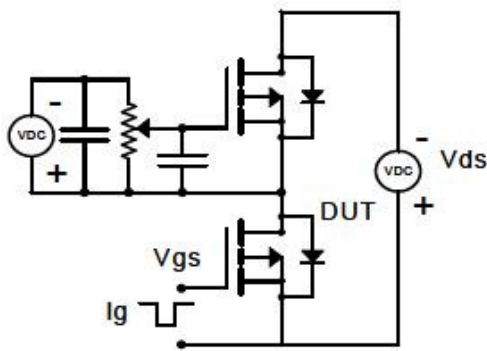




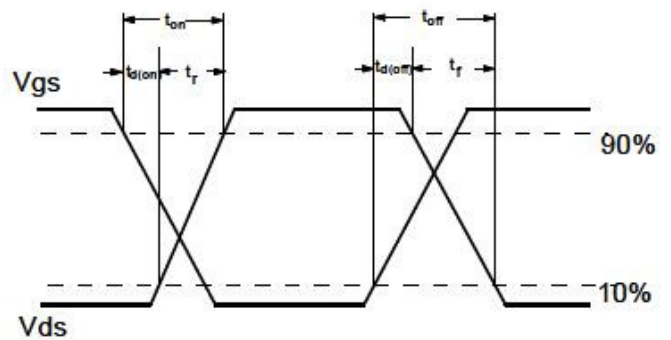
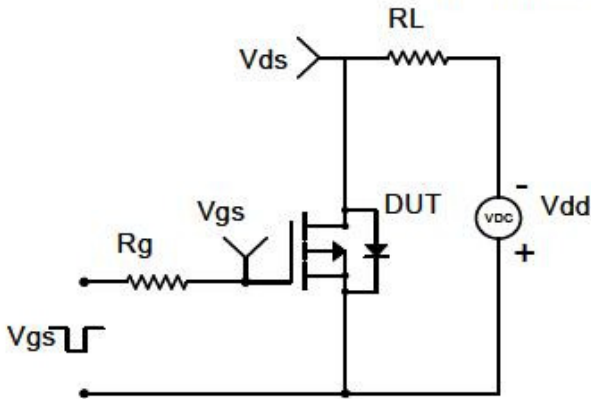


**Typical Characteristics**

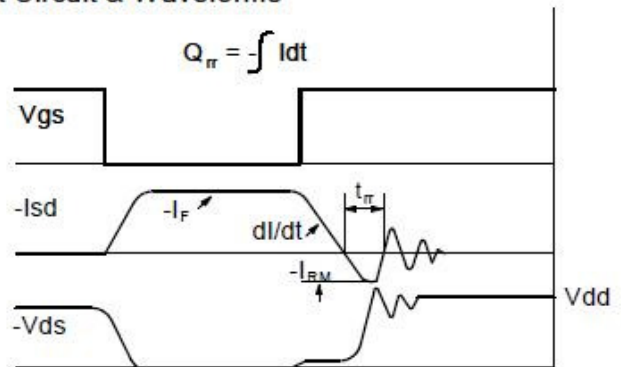
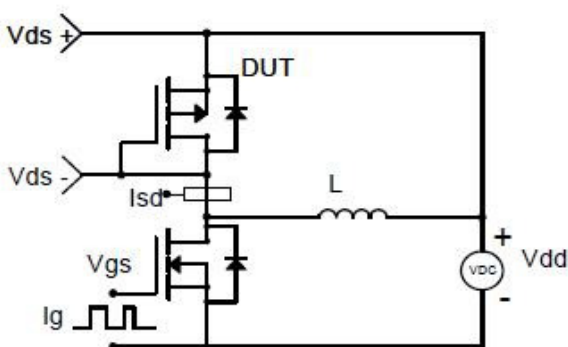
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

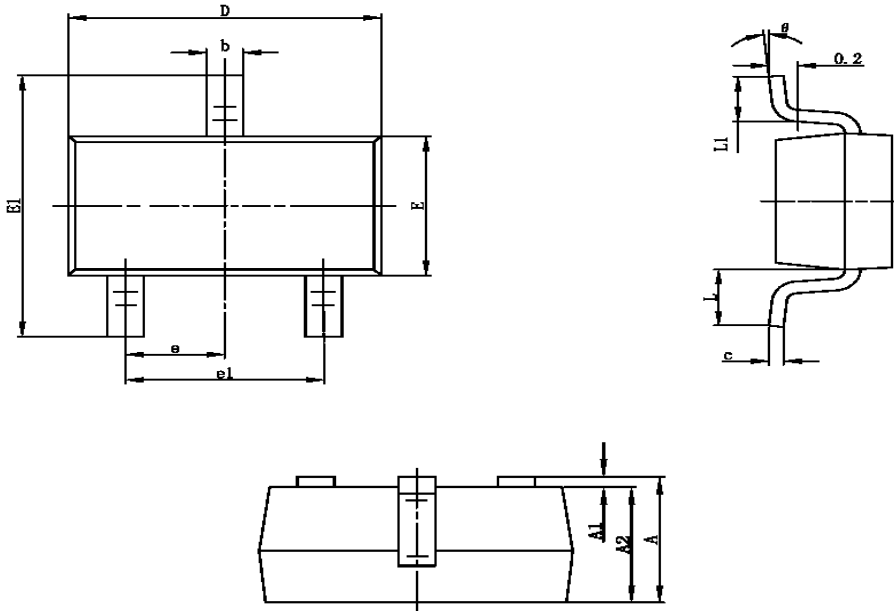


Diode Recovery Test Circuit & Waveforms





**Package Information ( SOT-23-3L )**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.400	0.012	0.016
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.700REF		0.028REF	
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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